PRODUCT DATA SHEET

Stand Off Technology (SOT)

for Solder Paste

Introduction

Stand Off Technology (SOT) is compatible with a wide range of Indium Corporation alloys and flux vehicles. This technology enables manufacturers to increase the stand off between their component and the board, facilitating easy cleaning and underfill processes. **SOT** can increase the stand off by (X%) when compared to solder paste that does not contain **SOT**.

Features

- Stand off height control (better way to word?)
- Improved underfill
- Easier cleaning
- Molding compounds
- Compatible with both Pb-free and Pb-containing alloys
- No-clean or water-soluble flux options

Alloys

Stand Off Technology has been tested with a wide variety of Indium Corporation alloys, including, SnAgCu, SnSb, Durafuse® LT and SnPb.

Alloy	Powder Size	Printing Metal Load
DFLTX-SOTC3B	T5MC	88~88.5%
Indalloy®256-SOTC3A	T5MC	88~88.5%

Packaging

Stand Off Technology is currently available in 600g cartridges. Alternate packaging options may be available upon request.

Storage and Handling

Freezer storage will prolong the shelf life of this solder paste. The shelf life of solder paste containing **SOT** is as follows:

Storage Conditions (unopened containers)	Shelf Life
<-10°C	6 months
Room temperature	72 hours

Solder paste packaged in cartridges and syringes should be stored tip down. When frozen, solder paste should be allowed to reach ambient working temperature prior to use. Generally, paste should be removed from the freezer at least 2 hours before use. Actual time to reach thermal equilibrium will vary with the container size and the solder paste temperature should be verified before use. Cartridges should be labeled with the date and time of opening.

Printing

The **SOT** particles may be larger than the solder powder spheres. Due to this, aperture size must be paid attention to closely. **SOT** particle size with vary based on the customers' desired stand off increase.

Cleaning

Dependent on flux vehicle, please refer to flux vehicle specific product data sheets.

Reflow

Dependent on alloy, please refer to alloy specific product data sheets or reach out to our technical service team.

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified.
Indium Corporation is an ISO 9001:2015 registered company.

From One Engineer To Another®

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